

LINEAR TECHNOLOGY MATERIALS DECLARATION

| LT3008IDC-1.8#TRPBF | | (Engineering Calculation) | | DFN 2mm X 2mm Exp. Pad | | | | |
|------------------------------------|----------------------------------|--------------------------------|------------|------------------------|-------------------|---------------------|----------------|-----------------|
| (printed on: 7/26/2011 6:11:48 AM) | | | | TOTAL MASS (g): | | 0.009349325 | | |
| COMPONENT | VENDOR/ | CONSTITUENT | CAS | CONSTITUENT | CONSTITUENT | CONSTITUENT | | |
| MATERIAL | INDUSTRY NAMES | NAME | NUMBER | MASS (g) | (PPM) OF MATERIAL | (PPM) OF TOTAL PKG. | | |
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.000429 | 1000000 | 45885.67 | | |
| Die Coat | Dow Corning | Silicone | 67762-90-7 | 0 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.002935 | 975000 | 313926.4 | | |
| | | Iron (Fe) | 7439-89-6 | 7.20E-05 | 24000 | 7701.091 | | |
| | | Phosphorus (P) | 7723-14-0 | 1.00E-06 | 300 | 106.9596 | | |
| | | Zinc (Zn) | 7440-66-6 | 2.00E-06 | 700 | 213.9192 | | |
| | | | | | | | | |
| | | Nickel (Ni) | 7440-02-0 | 0 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0 | 0 | 0 | | |
| | | Lead Frame Total: | | | | 0.00301 | 1000000 | 321948.4 |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000136325 | 1000000 | 14581.25 | | |
| | | External Plating Total: | | | | 0.000136325 | 1000000 | 14581.25 |
| | | Inter. Plating Ni | 7440-02-0 | 0 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 7.20E-05 | 1000000 | 7701.091 | | |
| | | Internal Plating Total: | | | | 7.20E-05 | 1000000 | 7701.091 |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000351 | 750000 | 37542.82 | | |
| | | Tin (Sn) | 7440-31-5 | 0 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0 | 0 | 0 | | |
| | | Metal Oxide | | 0 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0 | 0 | 0 | | |
| | | Resin (EP) | | 0.000117 | 250000 | 12514.27 | | |
| Die Attach Total: | | | | 0.000468 | 1000000 | 50057.09 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.000677 | 130000 | 72411.64 | | |
| | | Bromine (Br) | 40039-93-8 | 0 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.004481 | 860000 | 479285.9 | | |
| | | Antimony | 1309-64-4 | 0 | 0 | 0 | | |
| | | Trioxide (Sb2O3) | | | | | | |
| | | Metal Hydroxid | | 0 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 5.20E-05 | 10000 | 5561.899 | | |
| Encapsulation Total: | | | | 0.00521 | 1000000 | 557259.5 | | |
| Bond Wire | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 2.40E-05 | 1000000 | 2567.031 | | |
| Estimated | | | | | | | | |
| | | | | TOTAL MASS (g): | | 0.009349325 | | |